5 é / Descriptions

1.0A n µ É x ì ødý … v k V º MBF / xož
1.0A Surface Mount Glass Passivated Bridge Rectifier ÈMBF thin package Ä

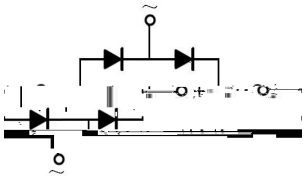
¤ ª / Features

ì ødý / Ì k F g 9 y < d < k 3 g v y ' k ~ … v Ý k 9 n µ É x k —)í D
}ož
Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current Ö1.0A, High Surge Current Capability, Designed for Surface Mount Application,HF Product.

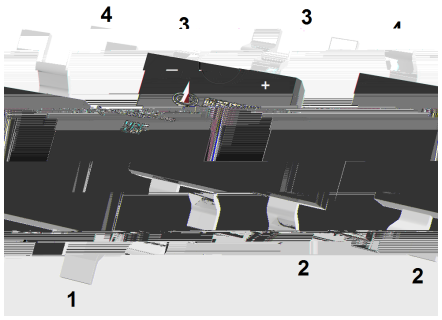
Ð ÷ / Applications

%² " (ož
General purpose.

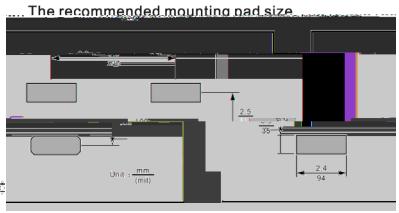
Ã W] Ô · / Equivalent Circuit



• Û - æ / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
3	Output Anode (+)



, M V / Marking

• - ~ ª ¢ož See Marking Instructions.

Ã a ? d / Absolute Maximum Ratings(Ta=25 ;)

@ ƒ Parameter	… Z Symbol	ƒ › Rating						% y Unit
		MB1F-10	MB2F-10	MB4F-10	MB6F-10	MB8F-10	MB10F-10	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T_c=125 °C	$I_{F(AV)}$	1.0						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	35						A
Typical Junction Capacitance[1] Å	C_j	13						pF
Typical Thermal Resistance[2] Å	R_{JA}	80						/W
	R_{JC}	25						
Operating and Storage Temperature Range	T_j ,T_{stg}	-55~+150						

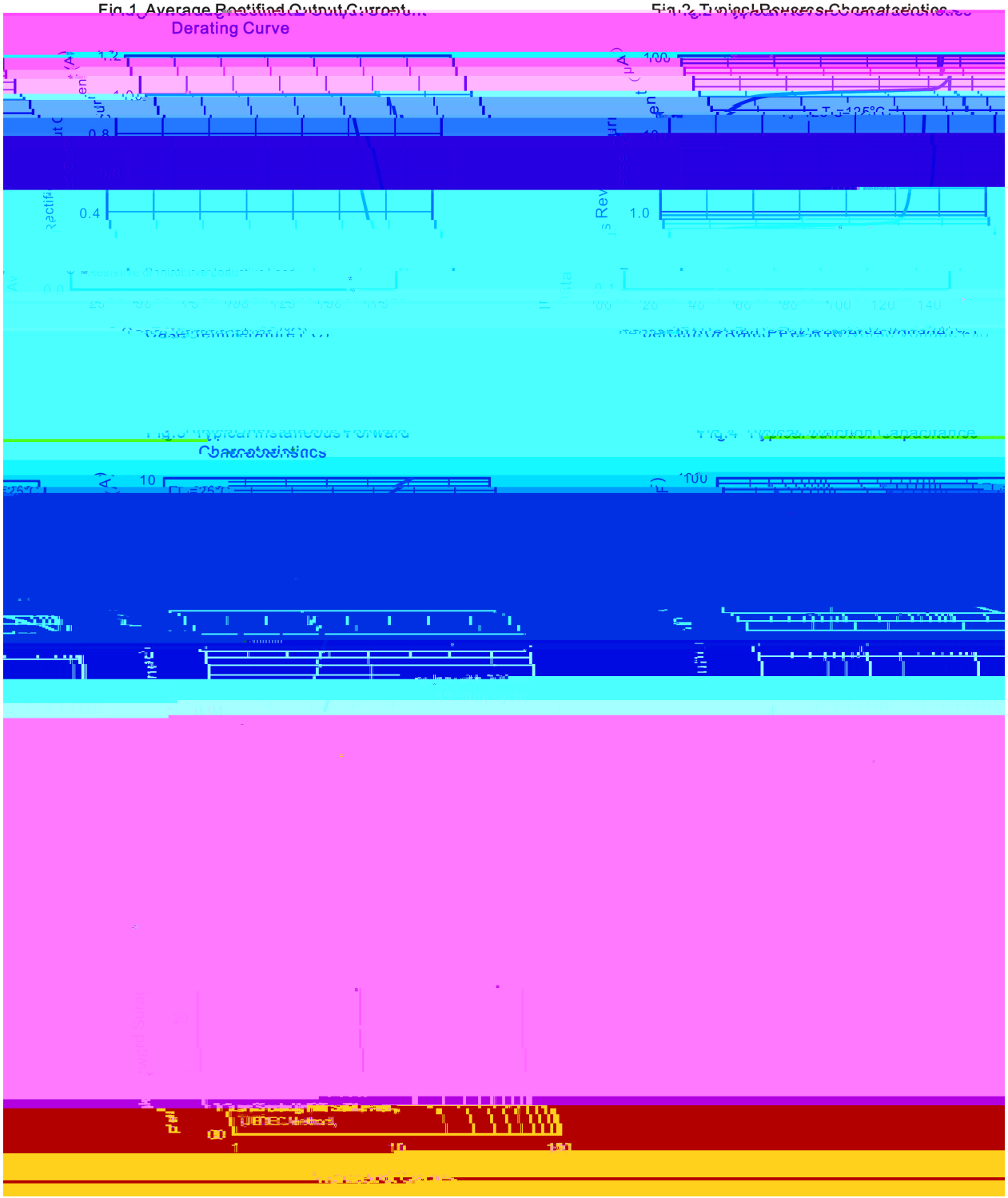
Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4 h 1.5" h 1.5" g 3.81 h 3.81 cm h copper pad.

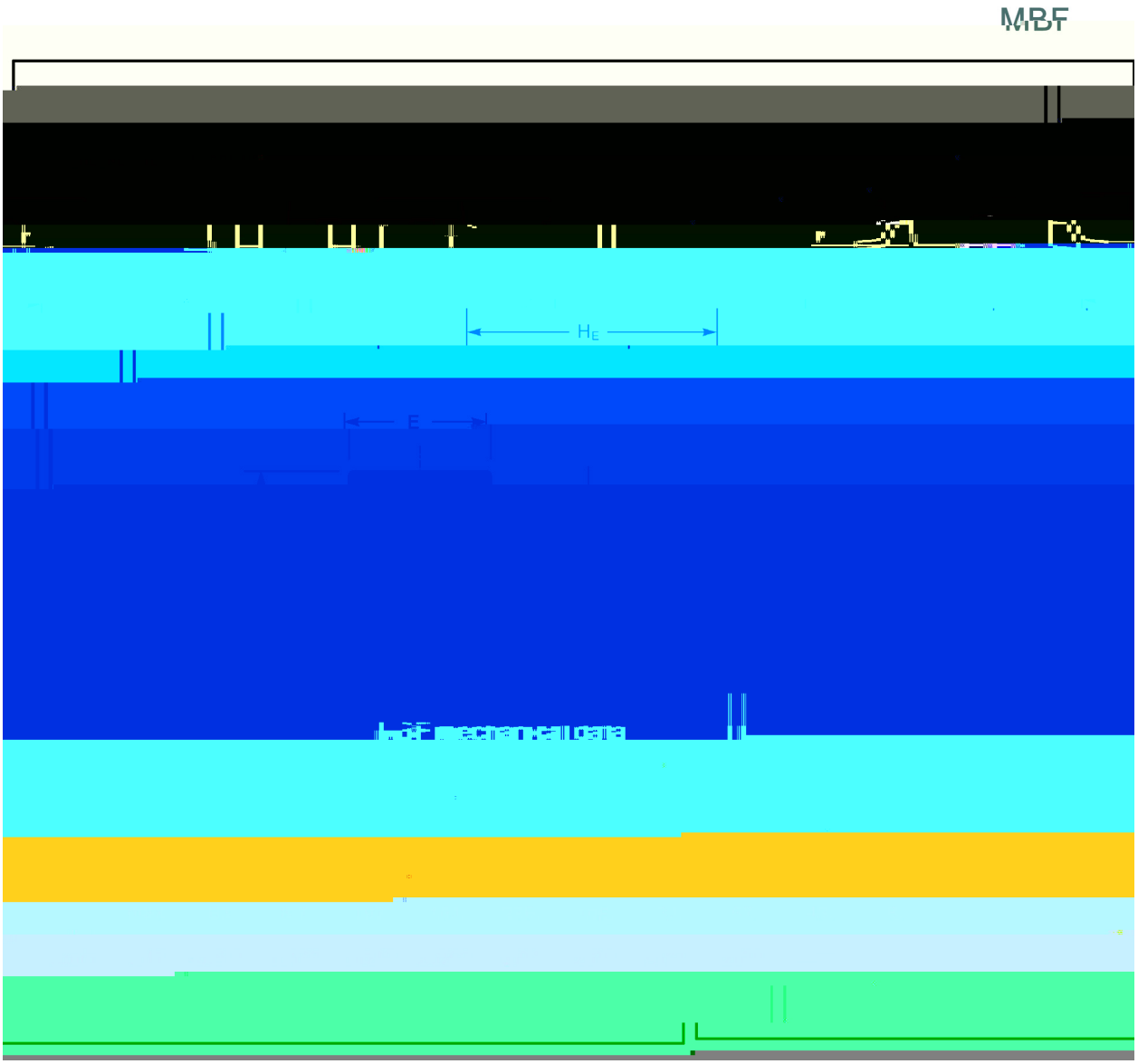
Ô4ì × ? d / Electrical Characteristics(Ta=25 ;)

@ ƒ Parameter	… Z Symbol	y ¡ Ú ^ Test Conditions	I Rating	% y Unit
Max Instantaneous Forward Voltage	V_F	I_F=1.0A	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25	5.0	A
		T_a=125	40	A

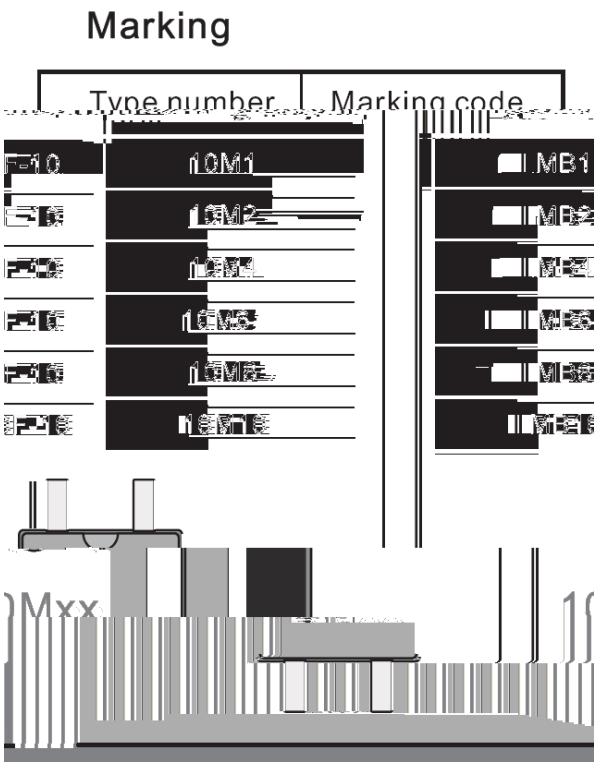
Ô ? d • Ž ¢ / Electrical Characteristic Curve



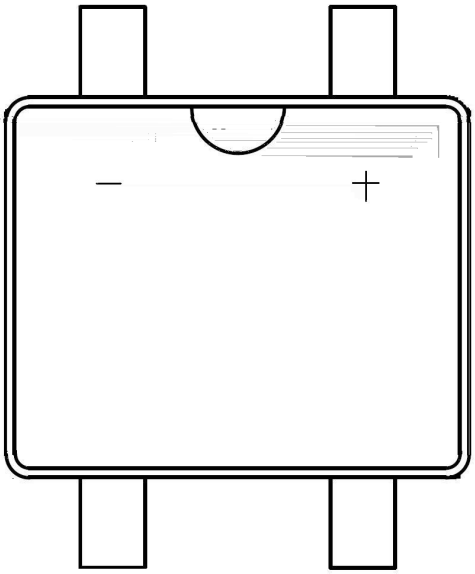
Ø ¤ =) ¢ / Package Dimensions



, M y ƒ / Marking Instructions



, M y ƒ / Marking Instructions



ª ¢

10M1 y º Z W A

**** y y

š WD t … • Ž ¢ (x /) / : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O T M 6

ª ¢ y

1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;

2o• Q › “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 - ž • y 10 r1 sec. Temp.:260 r5 - Time:10 r1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ˜ E	Units ;>û ¦H					Dimension ;>û p . (unit Æmm³)	
	Units/Reel / --	Reels/Inner Box -- /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Reel	Inner Box